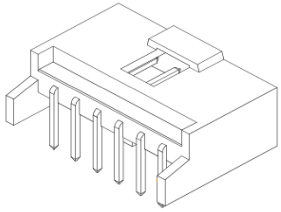


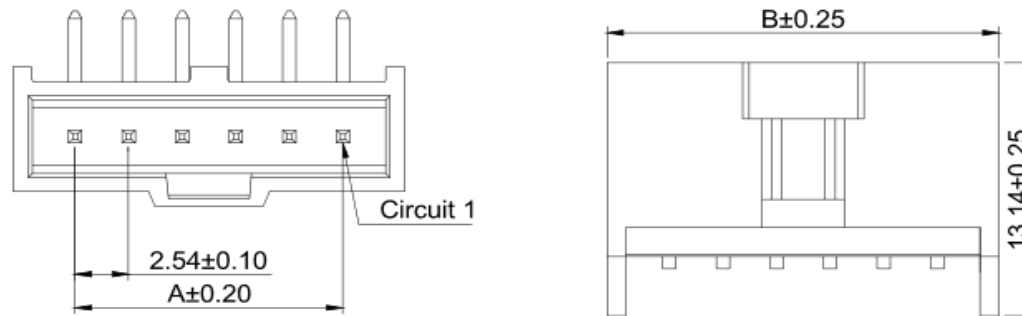
EDCON-COMPONENTS



Technical Description

Curent Rating:	3,0A
Voltage Rating:	250V AC,DC
Contact Resistance:	20mΩ max.
Withstanding Voltage:	1500VAC/ DC
Insulation Resistance:	1000MΩ Min
Operating Temperature:	.-40°c to + 105°C
Contact Material:	Brass
Contact Plating:	like Ordering
Insulator Material:	PBT + 30%G.F UL94V-0
Glow-Wire Test	IEC60335-1

Drawing

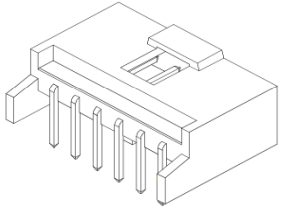


PCB Layout (mm)



					Wire to Board Connector (Wafer) Right Angle Pin Single Row					
					Part No.: T68N360					
DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023	Customer:
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 4		

EDCON-COMPONENTS



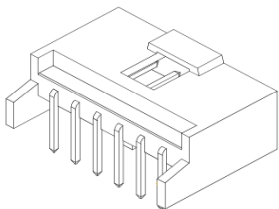
Dimension (mm)

No Pin	A	B	No Pin	A	B
2	2,54	8,43	30	73,66	79,55
3	5,08	10,97	31	76,20	82,09
4	7,62	13,51	32	78,74	84,63
5	10,16	16,05	33	81,28	87,17
6	12,70	18,59	34	83,82	89,71
7	15,24	21,13			
8	17,78	23,67			
9	20,32	26,21			
10	22,86	28,75			
11	25,40	31,29			
12	27,94	33,83			
13	30,48	36,37			
14	33,02	38,91			
15	35,56	41,45			
16	38,10	43,99			
17	40,64	46,53			
18	43,18	49,07			
19	45,72	51,61			
20	48,26	54,15			
21	50,80	56,69			
22	53,34	59,23			
23	55,88	61,77			
24	58,42	64,31			
25	60,96	66,85			
26	63,50	69,39			
27	66,04	71,93			
28	68,58	74,47			
29	71,12	77,01			

Wire to Board Connector (Wafer) Right Angle Pin Single Row	
Part No.:	T68N360
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.		2 from 4

EDCON-COMPONENTS



Ordering Informations

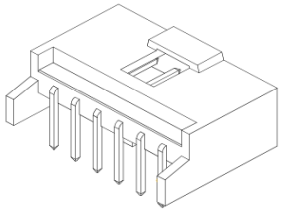
Serie	No. Of Position	Contact Plating	Contact Material	Color of Body	Special Function	Special Function	ROHS	Packing		
T68N360	02	GF	BR	BK	N	N	R	BU		

02= 2Pos.	TN= tinned	BR= Brass		N= No Function	N= No Function	R= ROHS Conform	BU= Bulk-Ware
2 ~ 20Pos.	GF= Gold Flash 0,25~0,5µ		BK= Black			N= NON ROHS Conform	TU= Tube Packing
	GA= Gold 3µ						TC= Tube w. Cap Packing
	GB= Gold 5µ						TR= Tape/Reel Packing w. Cap w. needed
	GC= Gold 10µ						IV= Individual Packing
	GD= Gold 15µ						
	GE= Gold 30µ						
	SA= Selectiv Gold 3µ						
	SB= Selectiv Gold 5µ						
	SC= Selectiv Gold 10µ						
	SD= Selectiv Gold 15µ						
	SE= Selectiv Gold 30µ						

**Wire to Board Connector
(Wafer) Right Angle Pin Single
Row**

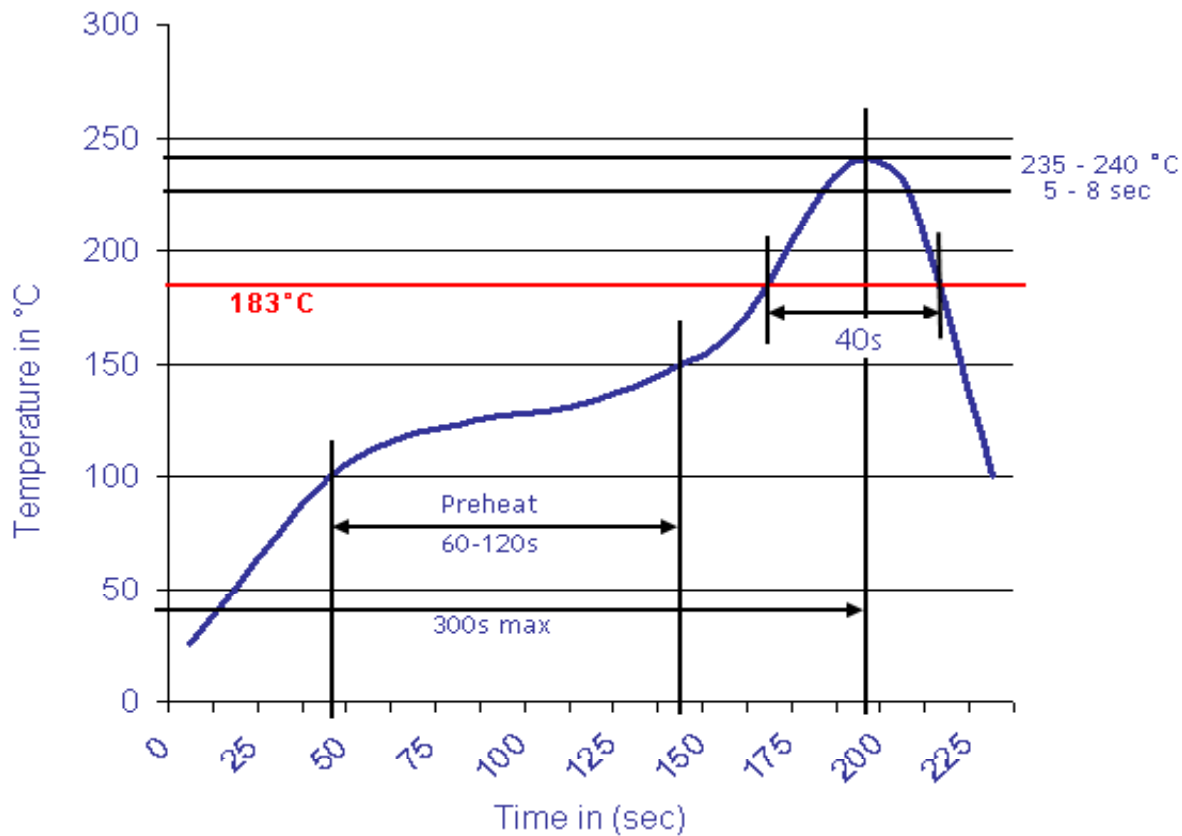
Part No.: **T68N360**

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023	Customer:
APPD:	Schumi			FINISH	Jamy		Sheet No.	3 from 4		



Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



Wire to Board Connector (Wafer) Right Angle Pin Single Row	
Part No.:	T68N360
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	23.03.2023
APPD:	Schumi			FINISH	Jamy		Sheet No.	4 from 4	